Wire Bonder
West bond 7476E

Description
An ultrasonic/thermosonic wedge-wedge wire bonder designed to interconnect wire leads to semi-conductor, hybrid or microwave devices.

Principle of operation
Bonds are made by the wedge-wedge technique using ultrasonic energy to attach wire at room temperature. The bonding tool is guided manually by the operator using hand/eye reference to bond targets and elevations.

Specifications / Capabilities
Bonds aluminum or gold wires.
17, 25 and 75µ wires (0.7, 1 and 3 mil).

Materials
Aluminum or gold wires.

Link
http://www.westbond.com/index.htm
http://www.westbond.com/7400espc.htm